

ABSTRACT OF THE DISCLOSURE

To provide an anisotropic conductive film which can respond to increasing pitch reduction of connection targets while maintaining connection reliability, and can be manufactured at a lower cost than conventional, and to provide a method of manufacturing the same. The anisotropic conductive film is provided with a porous film consisting of polymer, having numerous holes penetrating in a film thickness direction, the holes being in a honeycomb arrangement and having inner wall surfaces which curve outwards, a conductive material that fills the holes in the porous film, and an adhesive layer coated on both surfaces of the porous film. The porous film is formed by leaving a supporting substrate on which cast is a polymer solution where a polymer is dissolved in a hydrophobic, volatile organic solvent, under high humidity conditions.